PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tung-Hsing Lee	12/15/2008
Tien-Chang Chang	12/15/2008
Yuan-Hung Chung	12/15/2008

RECEIVING PARTY DATA

Name:	MEDIATEK INC.
Street Address:	No. 1, Dusing Rd. 1st, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12850640

CORRESPONDENCE DATA

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NAME OF SUBMITTER: HSIANG HUANG

Total Attachments: 2 source=906026#page1.tif source=906026#page2.tif

> PATENT REEL: 024791 FRAME: 0333

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ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name:	Tung-Hsing Lee	Nationality:	R,O.C.			
Name:	Tien-Chang Chang	_Nationality:	R.O.C.			
Name:	Yuan-Hung Chung	_Nationality:	R.O.C.			
Hereby sells, as ASSIGNEE(S)	ssigns and transfers to					
Name:	MEDIATEK INC.					
Address:	No. 1, Dusing Rd. 1st, Science-Based Industrial Park, Hsin-Chu 300, Taiwan, R.O.C.					
and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled: "SEAL RING STRUCTURE FOR INTEGRATED CIRCUITS"						
Which is found in:						
(a) + U.S. patent application executed on even date						
(b) U.S. patent application executed on						
(c)	U.S. application serial no					
(d)	patent no issued					

Assignment, Page 1 of 2

NPO#MTK-P0783-USA:0

CUST#MTKI-08-152US

F#NPO-P0002E-US1 DSB0-097U017193 and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this signing). (均發明人物必簽署上利日期:)

(Type name of inventor)

.

Signature of INVENTOR

Tung-Hsing Lee

Tien-Chang Chang

Yuan-Hung Chung

7- 06-0

Vhian-Hing Chun

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*F#*NPO-P0002E-US1 DSB0-097U017193

RECORDED: 08/05/2010